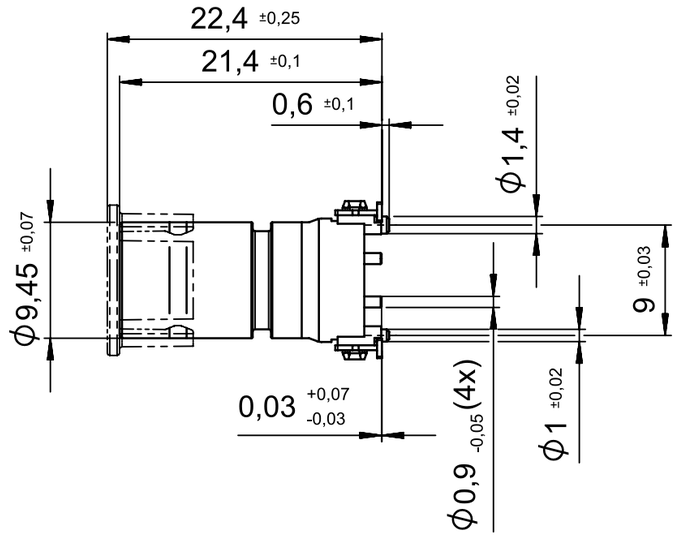
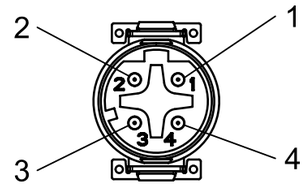
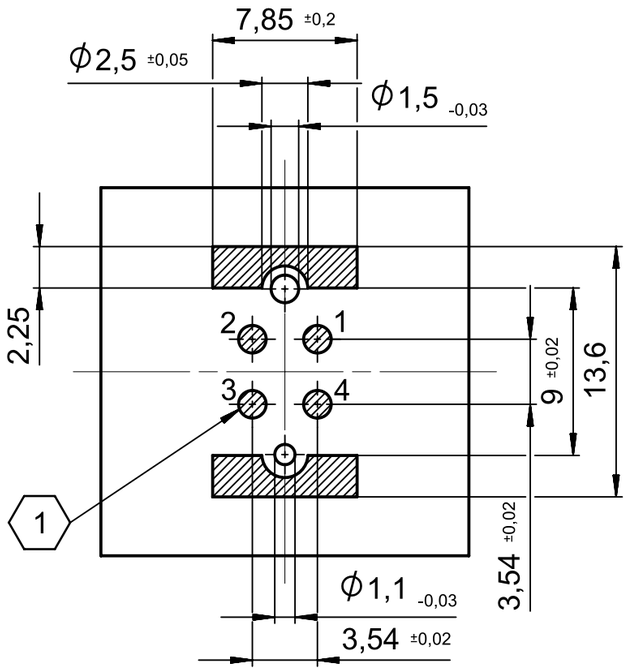




plug face male



PCB-layout (advice)



3:1

Coplanarity of all contacts and anchor plate | 0.1

Recommended solder paste thickness 150µm

(1) Further information on soldering process and recommended layout, see brochure "Connectors for SMT production"

- EN ISO 291 23/50

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page 1 of 1	description: SACC-CI-M12MSD-4P SMD T		

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